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## 

## **Quad, IEEE 802.3at/af PSE Controller** for Power-over-Ethernet

#### **General Description**

The MAX5980 is a quad, power-sourcing equipment (PSE) power controller designed for use in IEEE<sup>®</sup> 802.3at/af-compliant PSE. This device provides powered device (PD) discovery, classification, current limit, and load disconnect detection. The device supports both fully automatic operation and software programmability. The device also supports new 2-event classification and Class 5 for detection and classification of high-power PDs. The device supports single-supply operation, provides up to 70W to each port (Class 5 enabled), and still provides high-capacitance detection for legacy PDs.

The device features an I<sup>2</sup>C-compatible, 3-wire serial interface, and is fully software configurable and programmable. The device provides instantaneous readout of port current and voltage through the I<sup>2</sup>C interface. The device's extensive programmability enhances system flexibility, enables field diagnosis, and allows for uses in other, nonstandard applications.

The device is available in a space-saving, 32-pin TQFN (5mm x 5mm) power package and is rated for the automotive (-40°C to +105°C) temperature range.

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#### IEEE 802.3at/af Compliant

- 0.25Ω Current-Sensing Resistor
- Up to 70W per Port for PSE Applications
- ♦ 9-Bit Port Current and Voltage Monitoring
- ♦ I<sup>2</sup>C-Compatible, 3-Wire Serial Interface
- Supports Single-Supply Operation
- + High-Capacitance Detection for Legacy Devices
- Supports DC Load-Removal Detections
- Space-Saving, 32-Pin TQFN (5mm x 5mm) Power Package

#### Applications

**Features** 

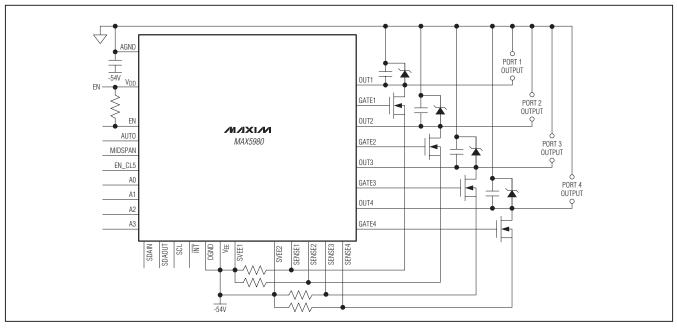
PSE-ICM Power-Sourcing Equipment (PSE) Switches/Routers Midspan Power Injectors

#### **Ordering Information**

PART	TEMP RANGE	PIN-PACKAGE
MAX5980GTJ+	-40°C to +105°C	32 TQFN-EP*

+Denotes a lead(Pb)-free/RoHS-compliant package. \*EP = Exposed pad.

#### Simplified Operating Circuit



#### 

Maxim Integrated Products 1

For pricing, delivery, and ordering information, please contact Maxim Direct at 1-888-629-4642, or visit Maxim's website at www.maxim-ic.com.

#### **ABSOLUTE MAXIMUM RATINGS**

(Voltages referenced to VEE, unless otherwise noted.)
AGND0.3V to +80V
DGND, SVEE0.3V to +0.3V
VDD0.3V to the lower (VAGND + 0.3V) and +4V
OUT0.3V to (VAGND + 0.3V)
GATE_, SENSE0.3V to +22V
A3, A2, A1, A0, MIDSPAN, EN_CL5, AUTO,
INT, SCL, SDAIN, SDAOUT, EN to DGND0.3V to +6V
Maximum Current into INT and OUT20mA
Maximum Current into OUTInternally Regulated

Continuous Power Dissipation (T<sub>A</sub> = +70°C) 32-Pin TQFN (derate 34.5mW/°C above +70°C)....2758.6mW Package Thermal Resistance (Note 1)

ØJA	+29 0/00
θJC	+1.7°C/W
Operating Temperature Range	40°C to +105°C
Storage Temperature Range	65°C to +150°C
Junction Temperature	+150°C
Lead Temperature (soldering, 10s)	+300°C
Soldering Temperature (reflow)	+260°C

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Note 1: Package thermal resistances were obtained using the method described in JEDEC specification JESD51-7, using a fourlayer board. For detailed information on package thermal considerations, refer to <u>www.maxim-ic.com/thermal-tutorial</u>.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### **ELECTRICAL CHARACTERISTICS**

 $(V_{AGND} = 32V \text{ to } 60V, V_{EE} = V_{DGND} = 0V, T_A = -40^{\circ}C \text{ to } +105^{\circ}C.$  All voltages are referenced to V<sub>EE</sub>, unless otherwise noted. Typical values are at V<sub>AGND</sub> = 54V, T<sub>A</sub> = +25^{\circ}C, and default register settings. Currents are positive when entering the pin, and negative otherwise.) (Note 2)

PARAMETER	SYMBOL	COND	MIN	ТҮР	MAX	UNITS	
POWER SUPPLIES							
Operating Voltage Range	Vagnd	Vagnd - Vee		32		60	V
Supply Currents	IEE	VOUT_ = VSENSE_ = VEE; INT, SDAOUT, and all logic inputs unconnected; VSCL = VSDAIN = VDD; measured at AGND in power mode after GATE_ pullup			5	7	mA
GATE DRIVER AND CLAMPING		·					
GATE_ Pullup Current	IPU	Power mode, gate dri	ive on, VGATE_ = VEE	-40	-50	-60	μA
GATE_ Pulldown Current	IPDW	Port SHDN mode ena VGATE_ = VEE + 10V		40		μA	
Strong Pulldown Current	IPDS	VSENSE_ = 500mV, Vo		25		mA	
External Gate Drive	VGS	VGATE VEE, power mode, gate-drive on		8.5	9.5	10.5	V
CURRENT LIMIT AND OVERCU	RRENT						
		Maximum VSENSE_	I <sub>LIM</sub> _ register set to 80h, Class 0–3	101	106.25	111.5	
Current-Limit Clamp Voltage	V <sub>SU_LIM</sub>	allowed during current-limit conditions,	I <sub>LIM</sub> _ register set to C0h, Class 4	200	212.5	225	mV
	V <sub>OUT_</sub> = (	V <sub>OUT</sub> = 0V (Note 3)	I <sub>LIM</sub> _ register set to C0h, Class 5	405	430	455	

#### **ELECTRICAL CHARACTERISTICS (continued)**

(VAGND = 32V to 60V, VEE = VDGND = 0V, TA = -40°C to +105°C. All voltages are referenced to VEE, unless otherwise noted. Typical values are at VAGND = 54V, TA = +25°C, and default register settings. Currents are positive when entering the pin, and negative otherwise.) (Note 2)

PARAMETER	SYMBOL	CONDITION	S	MIN	TYP	MAX	UNITS
			I <sub>CUT</sub> register set to 14h, Class 0 and 3	89	93.75	98.5	
Overcurrent Threshold after Startup	VCUT	Overcurrent VSENSE_ threshold allowed for $t \le t_{FAULT}$ after startup, VOUT_ = 0V	I <sub>CUT</sub> _ register set to 22h, Class 4	178	187.5	197	mV
			ICUT_ register set to 22h, Class 5	356	375	394	
		VAGND - VOUT_ above which the current-limit trip	I <sub>LIM</sub> register set to 80h		32		v
Foldback Initial Voltage	Vflbk_st	voltage starts folding back	I <sub>LIM</sub> register set to C0h		18		
Foldback Final Voltage	VFLBK_END	VAGND - VOUT_ above whic limit reaches VTH_FB	ch the current		46		V
Minimum Foldback Current-Limit Threshold	Vth_fb	Vout_ = Vagnd = 60V			35		mV
SENSE_ Input Bias Current		VSENSE_ = VEE				-2	μA
SUPPLY MONITORS							
VEE Undervoltage Lockout	VEE_UVLO	Vagnd - Vee, Vagnd - Vee		29		V	
VEE Undervoltage Lockout Hysteresis	VEE_UVLOH	Ports shut down if: VAGND - VEE_UVLO - VEE_UVLOH		3		V	
VEE Overvoltage Lockout	VEE_OV	Ports shut down if: VAGND - VAGND - VEE increasing		62		V	
V <sub>EE</sub> Overvoltage-Lockout Hysteresis	VEE_OVH				1		V
VEE Undervoltage	VEE_UV	VEE_UV event bit sets if: VA VEE_UV, VAGND - VEE incre			40		V
V <sub>DD</sub> Output Voltage	VDD	I <sub>DD</sub> = 0 to 10mA		3.0	3.3	3.6	V
V <sub>DD</sub> Undervoltage Lockout	Vdd_uvlo				2		V
Thermal-Shutdown Threshold	TSHD	Port is shut down and devic junction temperature excee temperature increasing (No		+140		°C	
Thermal-Shutdown Hysteresis	TSHDH	Temperature decreasing (N		20		°C	
OUTPUT MONITOR							
		$V_{OUT} = V_{AGND}$ , during idle				2	
OUT_ Input Current	IBOUT	VAGND - VEE = 48V, VOUT_ power-on mode			-70	μA	
Idle Pullup Resistance at OUT_	R <sub>DIS</sub>	Detection and classificatior shut down	0.7	1	1.25	MΩ	
PGOOD High Threshold	PGTH	VOUT VEE, OUT_ decreas	1.5	2.0	2.5	V	

#### **ELECTRICAL CHARACTERISTICS (continued)**

 $(V_{AGND} = 32V \text{ to } 60V, V_{EE} = V_{DGND} = 0V, T_{A} = -40^{\circ}C \text{ to } +105^{\circ}C.$  All voltages are referenced to V\_{EE}, unless otherwise noted. Typical values are at V\_{AGND} = 54V, T\_{A} = +25^{\circ}C, and default register settings. Currents are positive when entering the pin, and negative otherwise.) (Note 2)

PARAMETER	SYMBOL	CONE	DITIONS	MIN	ТҮР	MAX	UNITS
PGOOD Hysteresis	PGHYS				220		mV
PGOOD Low-to-High Glitch Filter	tpgood	Time V <sub>OUT</sub> - V <sub>EE</sub> ha set the PGOOD_ bit	2		4	ms	
LOAD DISCONNECT							
DC Load Disconnect Threshold	VDCTH	Minimum VSENSE_ all disconnect (DC disc V <sub>OUT</sub> _ = 0V		1.25	1.875	2.5	mV
Load Disconnect Time	tDISC	Time from VSENSE_ < shutdown (Note 5)	< VDCTH to gate	300		400	ms
DETECTION							
Detection Probe Voltage (First Phase)	VDPH1	VAGND - VDET during phase	g the first detection	3.8	4	4.2	V
Detection Probe Voltage (Second Phase)	VDPH2	VAGND - VDET during phase	g the second detection	8.8	9.1	9.4	V
Current-Limit Protection	IDLIM	V <sub>OUT</sub> = V <sub>AGND</sub> , cur OUT_ during detection	rent measured through on	1.50		2	mA
Short-Circuit Threshold	VDCP	If V <sub>AGND</sub> - V <sub>OUT</sub> < V detection phase, a s detected		1.5		V	
Open-Circuit Threshold	ID_OPEN	First point measurem for open condition		12.5		μA	
Resistor Detection Window	Rdok	(Note 5)		19		26.5	kΩ
Resistor Rejection Window	Rdbad	Detection rejects low Detection rejects hig		32		15.2	kΩ
CLASSIFICATION							
Classification Probe Voltage	VCL	VAGND - VOUT_ durir	ng classification	15.5		20	V
Current-Limit Protection	ICL_LIM	$V_{OUT} = V_{AGND}$ , cur through OUT_	rent measured	65	75	86	mA
Classification Event Timing	tCL_E			14	18	22	ms
Mark Event Voltage	Vmark	VAGND - VDET during	g mark event	8		9.6	V
Mark Event Current Limit	IMARK_LIM	V <sub>DET</sub> = V <sub>AGND</sub> , during mark event measure current through DET		34	40	46	mA
Mark Event Timing	<sup>t</sup> MARK_E			7	9	11	ms
			Class 0, Class 1	5.5	6.5	7.5	
		Classification	Class 1, Class 2	13.0	14.5	16.0	
Classification Current Thresholds	ICL	current thresholds	Class 2, Class 3	21	23	25	mA
	102	between classes	Class 3, Class 4	31	33	35	
			Class 4 upper limit (Note 6)	45	48	51	

#### **ELECTRICAL CHARACTERISTICS (continued)**

 $(V_{AGND} = 32V \text{ to } 60V, V_{EE} = V_{DGND} = 0V, T_{A} = -40^{\circ}C \text{ to } +105^{\circ}C.$  All voltages are referenced to V<sub>EE</sub>, unless otherwise noted. Typical values are at V<sub>AGND</sub> = 54V, T<sub>A</sub> = +25^{\circ}C, and default register settings. Currents are positive when entering the pin, and negative otherwise.) (Note 2)

PARAMETER	SYMBOL	CONDITIONS		MIN	ТҮР	MAX	UNITS	
DIGITAL INPUTS/OUTPUTS (Vo	Itages Refere	enced to VEE)						
Digital Input Low	VIL					0.8	V	
Digital Input High	VIH			2			V	
Internal Input Pullup/Pulldown Resistor	Rdin	Pullup (pulldown) re to set default level	esistor to V <sub>DD</sub> (DGND)	25	50	75	kΩ	
Open-Drain Output Low Voltage	Vol	ISINK = 10mA				0.4	V	
Open-Drain Leakage	IOL	Open-drain high im	pedance, V <sub>OUT</sub> = 3.3V			1	μA	
SCL, SDAIN Input Leakage	IDL	Input connected to	the pull voltage			1	μA	
Hardware Reset Pulse Width		Minimum low pulse to a hardware reset	duration on EN to lead	120			μs	
TIMING	1							
Startup Time	tSTART		a current limit set by starts when the GATE_	50	60	70	ms	
Fault Time	tfault	Time allowed for an VFLT_LIM after start	overcurrent fault set by up	50	60	70	ms	
Current Limit	t <sub>LIM</sub>	Time during after st	artup (Note 7)	50	60	70	ms	
Port_Turn-Off Time	tOFF	Minimum delay bet does not apply in a		0.1		ms		
Detection Reset Time		Time allowed for the before detection sta	e port voltage to reset arts		80		ms	
Detection Time	t <sub>DET</sub>	Maximum time allow completed	wed before detection is			330	ms	
Midspan Mode Detection Delay	tDMID			2			S	
Classification Time	tCLASS	Time allowed for cla	assification		19	25	ms	
VEE_UVLO Turn-On Delay	tDLY	Time V <sub>AGND</sub> must k threshold before the	be above the V <sub>EE_UVLO</sub>	2		4	ms	
Restart Timer	<sup>t</sup> RESTART	Time the device waits before turning on after an overcurrent fault, MIDSPAN disabled		0.8	0.96	1.1	S	
Startup Sequence Delay	tSEQ	Time between any port power-up in auto mode			0.5		S	
ADC PERFORMANCE (Power-O	n Mode)							
Resolution					9		Bits	
			$T_A = -5^{\circ}C \text{ to } +85^{\circ}C$			2.5		
0	Voltage re		$T_{A} = -40^{\circ}C \text{ to } +105^{\circ}C$			3	1	
Offset Error			$T_A = -5^{\circ}C \text{ to } +85^{\circ}C$			2.5	LSB	
		Current reading	$T_{A} = -40^{\circ}C \text{ to } +105^{\circ}C$			3	1	

#### **ELECTRICAL CHARACTERISTICS (continued)**

 $(V_{AGND} = 32V \text{ to } 60V, V_{EE} = V_{DGND} = 0V, T_{A} = -40^{\circ}C \text{ to } +105^{\circ}C.$  All voltages are referenced to V\_{EE}, unless otherwise noted. Typical values are at  $V_{AGND} = 54V$ ,  $T_{A} = +25^{\circ}C$ , and default register settings. Currents are positive when entering the pin, and negative otherwise.) (Note 2)

PARAMETER	SYMBOL	CONDITIONS			TYP	MAX	UNITS	
			$T_A = -5^{\circ}C \text{ to } +85^{\circ}C$	-0.5		+4		
		Gain error voltage	$T_A = -40^{\circ}C \text{ to } +105^{\circ}C$	-1		+4.5	%	
Gain Error			$T_A = -5^{\circ}C \text{ to } +85^{\circ}C$	-2		+2		
		Gain error current	$T_A = -40^{\circ}C \text{ to } +105^{\circ}C$	-2.5		+2.5		
			$T_A = -5^{\circ}C \text{ to } +85^{\circ}C$	-0.5		+4.5	<u> </u>	
VEE Voltage Accuracy		VAGND - VEE = 48V	TA = -40°C to +105°C	-0.5		+5	%	
Integral Nonlinearity	INL					1	LSB	
Differential Nonlinearity	DNL					1	LSB	
Current Reading Range		Classes 0-4			1			
Current Reading Range		Class 5			2		- A	
Current LSB Step Size		Classes 0–4			1.956		mA	
Current LSB Step Size		Class 5			3.912			
Voltage Reading Range		All classes			95.6		V	
Voltage LSB Step Size		All classes			187		mV	
<b>TIMING CHARACTERISTICS (3-V</b>	Vire Fast Mo	de)						
Serial Clock Frequency	fscl			10		400	kHz	
Bus Free Time Between a STOP and START Condition	tBUF			1.3			μs	
Hold Time for a START Condition	thd, sta			0.6			μs	
Low Period of the SCL Clock	tLOW			1.3			μs	
High Period of the SCL Clock	thigh			0.6			μs	
Setup Time	tsu, sta	START and STOP co	onditions	0.6			μs	
Data Hold Time	tup pat	Receive		0				
Data Hold Time	thd, dat	Transmit	100		300	ns		
Data in Setup Time	tsu, dat			100			ns	
Cumulative Clock Low Extend Time	tLOW_EXT					25	ms	
Fall Time of SDAOUT Transmitting	tF	(Note 8)				250	ns	
Setup Time for STOP Condition	tsu, sto			0.6			μs	
Pulse Width of Spike Suppressed	tSP	(Note 8)			30		ns	

**Note 2:** Production testing done at +25°C. Overtemperature limits are guaranteed by design and not production tested.

Note 3: The current-limit thresholds are programmed through the I<sup>2</sup>C interface (see the *Register Map and Description* section and Table 41).

**Note 4:** Functional test is performed over thermal shutdown entering test mode.

**Note 5:** RDOK = (VOUT2 - VOUT1)/(IOUT2 - IOUT1). VOUT1, VOUT2, IOUT1, and IOUT2 represent the voltage at OUT\_ and the current into OUT\_ during phase 1 and 2 of the detection, respectively.

Note 6: If Class 5 is enabled, this value is the classification current threshold from Class 4 to Class 5, and classification currents between 51mA and I<sub>CL\_LIM</sub> will be classified as Class 5.

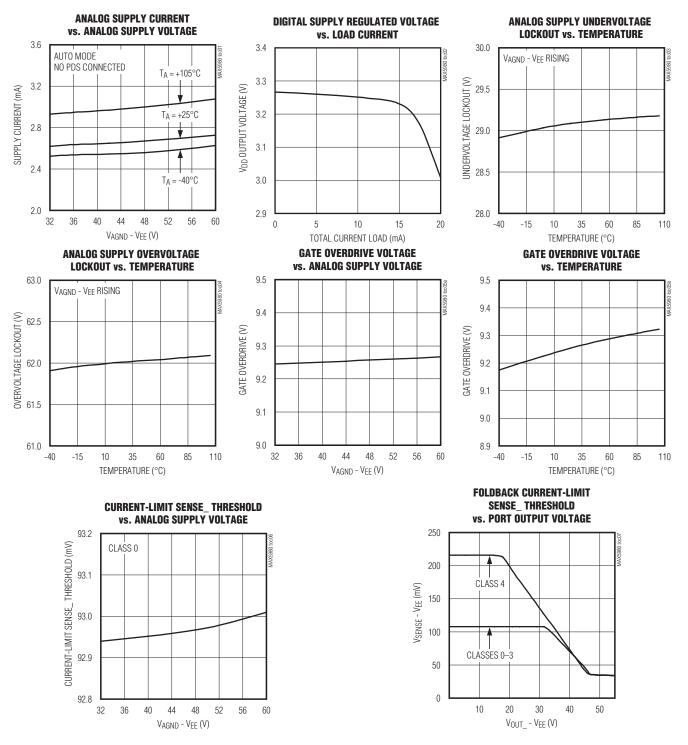
Note 7: Default value. The fault timer can be reprogrammed through the I<sup>2</sup>C interface (TLIM\_[3:0]).

Note 8: Guaranteed by design. Not subject to production testing.



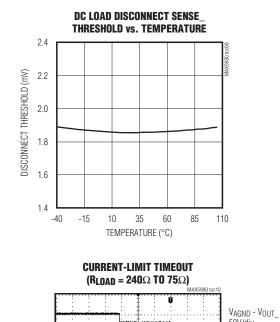
#### **Typical Operating Characteristics**

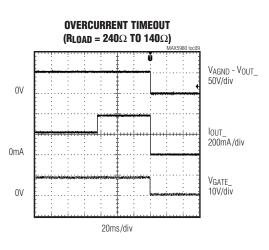
 $(V_{AGND} = 32V \text{ to } 60V, V_{EE} = V_{DGND} = 0V, T_A = -40^{\circ}C \text{ to } +105^{\circ}C.$  All voltages are referenced to V<sub>EE</sub>, unless otherwise noted. Typical values are at V<sub>AGND</sub> = 54V, T<sub>A</sub> = +25^{\circ}C, ENDPOINT mode, and default register settings with a Class 0 PD, unless otherwise noted.)



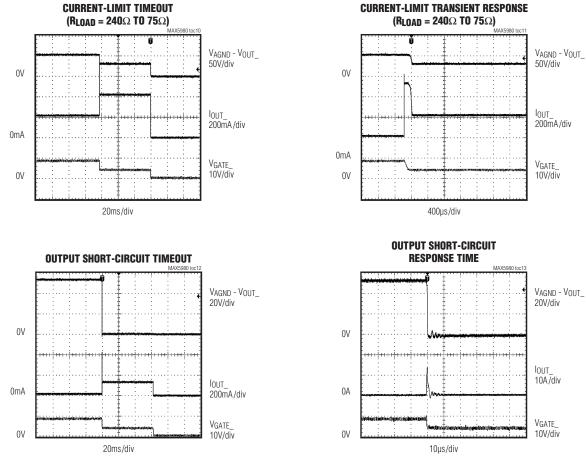
#### **Typical Operating Characteristics (continued)**

 $(V_{AGND} = 32V \text{ to } 60V, V_{EE} = V_{DGND} = 0V, T_A = -40^{\circ}C \text{ to } +105^{\circ}C.$  All voltages are referenced to V<sub>EE</sub>, unless otherwise noted. Typical values are at V<sub>AGND</sub> = 54V, T<sub>A</sub> = +25^{\circ}C, ENDPOINT mode, and default register settings with a Class 0 PD, unless otherwise noted.)





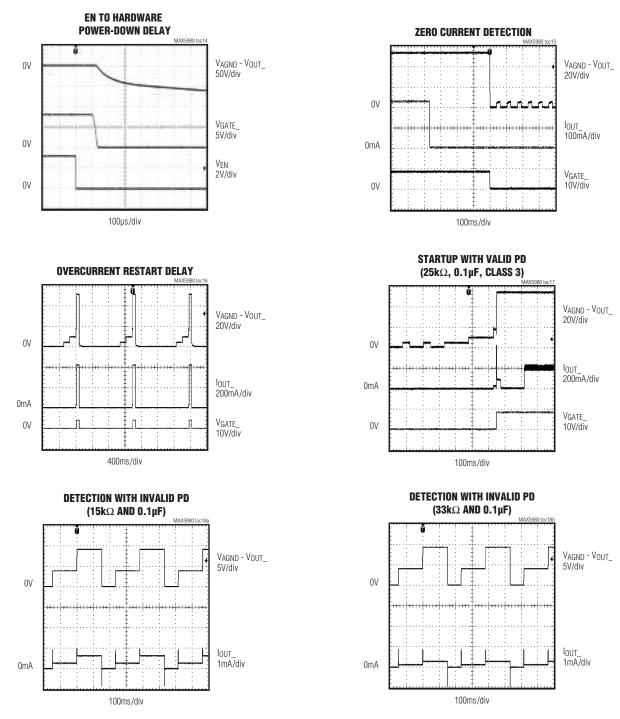
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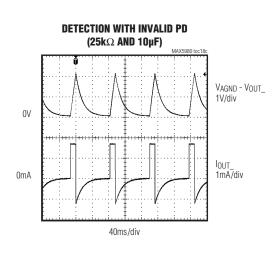
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 $(V_{AGND} = 32V \text{ to } 60V, V_{EE} = V_{DGND} = 0V, T_A = -40^{\circ}C \text{ to } +105^{\circ}C.$  All voltages are referenced to V<sub>EE</sub>, unless otherwise noted. Typical values are at V<sub>AGND</sub> = 54V, T<sub>A</sub> = +25^{\circ}C, ENDPOINT mode, and default register settings with a Class 0 PD, unless otherwise noted.)

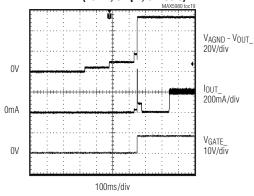


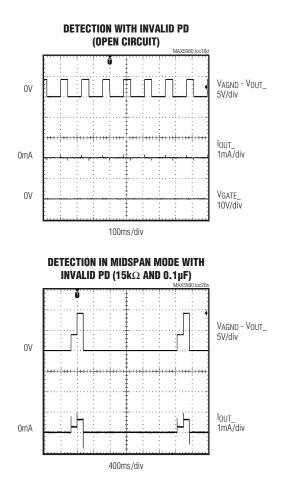
#### **Typical Operating Characteristics (continued)**

 $(V_{AGND} = 32V \text{ to } 60V, V_{EE} = V_{DGND} = 0V, T_{A} = -40^{\circ}C \text{ to } +105^{\circ}C.$  All voltages are referenced to V\_{EE}, unless otherwise noted. Typical values are at V\_{AGND} = 54V, T\_{A} = +25^{\circ}C, ENDPOINT mode, and default register settings with a Class 0 PD, unless otherwise noted.)



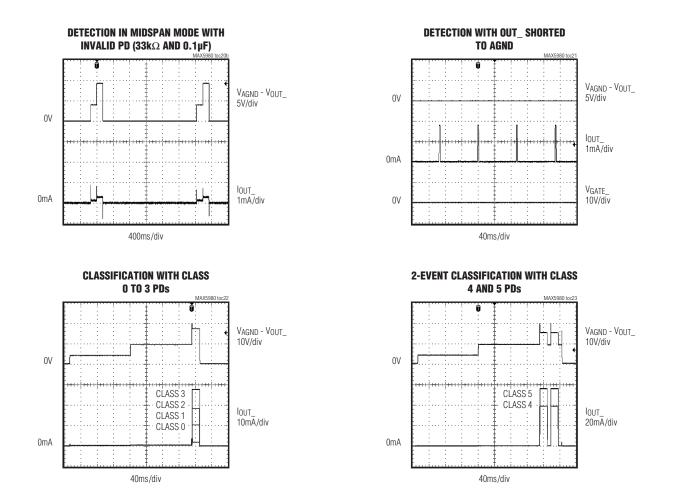




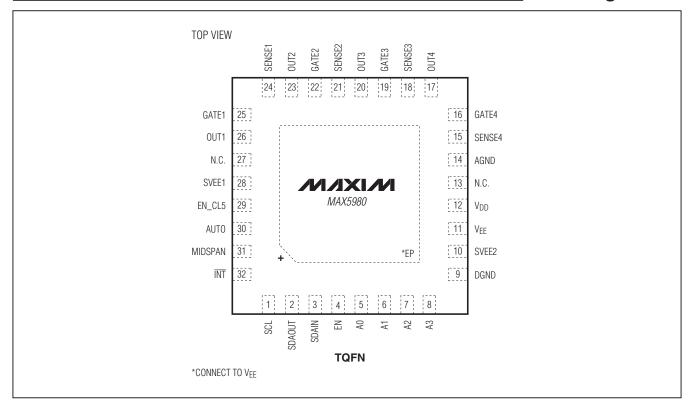


#### **Typical Operating Characteristics (continued)**

(VAGND = 32V to 60V, VEE = VDGND = 0V, TA = -40°C to +105°C. All voltages are referenced to VEE, unless otherwise noted. Typical values are at VAGND = 54V, TA = +25°C, ENDPOINT mode, and default register settings with a Class 0 PD, unless otherwise noted.)



**\_Pin Configuration** 



#### **Pin Description**

PIN	NAME	FUNCTION
1	SCL	3-Wire Serial Interface Input Clock Line. Referenced to DGND. Connect to DGND if the I <sup>2</sup> C interface is not used.
2	SDAOUT	Serial Interface Data Line Output. Referenced to DGND. Connect to DGND if the I <sup>2</sup> C interface is not used.
3	SDAIN	Serial Interface Data Line Input. Referenced to DGND. Connect to DGND if the I <sup>2</sup> C interface is not used.
4	EN	EN Input. Referenced to DGND. Connect EN to V <sub>DD</sub> externally through a pullup resistor to enable normal operation. See the <i>Hardware Power-Down</i> section for details.
5, 6, 7, 8	A0, A1, A2, A3	Slave Address Bits 0, 1, 2, 3 (Respectively). Referenced to DGND. The slave address bits are used to form bits 3, 2, 1, and 0 of the device address (0:1:0:A3:A2:A1:A0; see Table 3). The slave address bits are internally pulled up to $V_{DD}$ . Leave them unconnected to use the default device address (0101111). Connect one or more to DGND to change the device address. The slave address is latched-in after the device is powered up or after a reset condition.
9	DGND	Digital Low-Side Supply Input. Connect to VEE externally.
10	SVEE2	Port 3/4 Current-Sense Negative Terminal Input. Use Kelvin-sensing technique in PCB layout for best accuracy current sensing.

### \_Pin Description (continued)

PIN	NAME	FUNCTION					
11	VEE	Analog Low-Side Supply Input. Bypass with an external 100V, 0.1 $\mu F$ ceramic capacitor between AGND and VEE.					
12	V <sub>DD</sub>	Digital High-Side Supply Output. Bypass with an external RC network; see the V <sub>DD</sub> Power Supply ection for details.					
13, 27	N.C.	No Connection. Not internally connected. Leave N.C. unconnected.					
14	AGND	Analog High-Side Supply Input					
15, 18, 21, 24	SENSE4, SENSE3, SENSE2, SENSE1	Current-Sense Positive Terminal Inputs. Connect to the source of the external power MOSFET and connect a $0.25\Omega$ current-sense resistor between SENSE_ and SVEE Use Kelvin-sensing technique in PCB layout for best accuracy current sensing.					
16, 19, 22, 25	GATE4, GATE3, GATE2, GATE1	Port_MOSFET Gate Drivers. Connect GATE_ to the gate of the external power MOSFET (see the <i>Typical Operating Circuit</i> ).					
17, 20, 23, 26	OUT4, OUT3, OUT2, OUT1	Port Output Voltage Senses. Connect OUT_ to the port output.					
28	SVEE1	Port 1/2 Current-Sense Negative Terminal Input. Use Kelvin sensing technique in PCB layout for best accuracy current sensing.					
29	EN_CL5	Class 5 Enable Input. Referenced to DGND. EN_CL5 is internally pulled down to DGND. Leave unconnected to disable the classification for Class 5 devices (IEEE 802.3at-compliant mode). Connect EN_CL5 to V <sub>DD</sub> to enable the classification of Class 5 devices. EN_CL5 is latched in after the device is powered up or after a reset condition.					
30	AUTO	Auto/Shutdown Mode Input. Referenced to DGND. AUTO is internally pulled up to V <sub>DD</sub> . Leave unconnected to put the device into auto mode by default. Connect AUTO to DGND instead to set the default mode to shutdown. In either configuration, the software can change the operating mode of the device. AUTO is latched in after the device is powered up or after a reset condition.					
31	MIDSPAN	Detection Collision Avoidance Logic Input. Referenced to DGND. MIDSPAN is internally pulled up to V <sub>DD</sub> . Leave unconnected to activate midspan mode, or connect to DGND to disable this function. MIDSPAN is latched in after the device is powered up or after a reset condition.					
32	ĪNT	Open-Drain Interrupt Output. Referenced to DGND. INT is pulled low whenever an interrupt is sent to the microcontroller. See the <i>Interrupt</i> section for details. Connect to DGND if the I <sup>2</sup> C interface is not used.					
_	EP	Exposed Pad. EP is internally connected to VEE. Connect EP to VEE externally.					

SCL SDAIN SDAOUT EN -OUT\_ CURRENT SENSING VOLTAGE PROBING SERIAL PORT AND CURRENT-LIMIT INTERFACE (SPI) CONTROL AUTO MIDSPAN 9-BIT ADC VOLTAGE DETECTION AND PORT STATE SENSING **REGISTER FILE** CLASSIFICATION CONVERTER EN\_CL5 MACHINE (SM) CONTROL A3-A0 SENSE\_  $V_{\text{EE}}$ POWER GATE\_ ENABLE GATE-DRIVE CONTROL INT CENTRAL LOGIC UNIT (CLU) FAST DISCHARGE ΜΛΧΙΛΙ MAX5980 AGND ANALOG INTERNAL DGND CURRENT LIMIT, BIAS AND ► REFERENCES FOLDBACK CONTROL OVERCURRENT, SUPPLY AND SUPPLIES MONITORS AND OPEN-CIRCUIT VEE SENSING, AND SENSE FOLDBACK CONTROL THRESHOLD SETTINGS Vdd DIGITAL BIAS SVEE1 SVEE2

**Functional Diagram** 

#### **Detailed Description**

The MAX5980 is a quad PSE power controller designed for use in IEEE 802.3at/af-compliant PSE. This device provides PD discovery, classification, current limit, and load disconnect detections. The device supports both fully automatic operation and software programmability. The device also supports new 2-event classification and Class 5 for detection and classification of high-power PDs. The device supports single-supply operation, provides up to 70W to each port (Class 5 enabled), and still provides high-capacitance detection for legacy PDs.

The device features an I<sup>2</sup>C-compatible, 3-wire serial interface, and is fully software configurable and programmable. The device provides instantaneous readout of port current and voltage through the I<sup>2</sup>C interface. The device provides input undervoltage lockout (UVLO), input overvoltage lockout (OVLO), overtemperature protection, and output voltage slew-rate limit during startup.

#### Reset

The device is reset by any of the following conditions:

- Power-up/down. Reset condition is asserted once VEE falls below the UVLO threshold.
- Hardware reset. To initiate a hardware reset, pull EN low to DGND for at least 100µs. Hardware reset clears once, EN returns high to V<sub>DD</sub>, and all registers are set to their default states.
- Software reset. To initiate a software reset, write a logical 1 to the RESET\_IC register (R1Ah[4]) any time after power-up. Reset clears automatically, and all registers are set to their default states.
- Thermal shutdown. The device enters thermal shutdown at +140°C. The device exits thermal shutdown and is reset once the temperature drops below 120°C.

During normal operation, changes to the address inputs, MIDSPAN, EN\_CL5, and AUTO are ignored, and they can be changed at any time prior to a reset state. At the end of a reset event, the device latches in the state of these inputs.

#### **Port Reset**

Set RESET\_P\_ (R1Ah[3:0]) high anytime during normal powered operation to turn off port\_, disable detection and classification, and clear the Port\_ Event and Status registers. If a port is not powered, setting RESET\_P\_ high for that port has no effect. Individual port reset does not initiate a global device reset.

#### Midspan Mode

In midspan mode, the device adopts cadence timing during the detection phase. When cadence timing is enabled and a failed detection occurs, the ports wait at least 2s before attempting to detect again. Midspan mode is activated by setting MIDSPAN high and then powering or resetting the device. Alternatively, midspan mode can be software programmed individually for each port by setting MIDSPAN\_ (R15h[3:0], Table 23) to a logical 1. By default, the MIDSPAN input is internally pulled high, enabling cadence timing. Force MIDSPAN low to disable this function.

#### **Operation Modes**

The device provides four operating modes to suit different system requirements. By default, auto mode allows the device to operate automatically at its default settings without any software. Semiautomatic mode automatically detects and classifies devices connected to the ports, but does not power a port until instructed to by software. Manual mode allows total software control of the device and is useful for system diagnostics. Shutdown mode terminates all activities and securely turns off power to the ports.

Switching between auto, semiautomatic, and manual mode does not interfere with the operation of an output port. When a port is set into shutdown mode, all port operations are immediately stopped and the port remains idle until shutdown mode is exited.

#### Auto (Automatic) Mode

By default, when the auto input is unconnected, the device enters auto mode after power-up or when the reset condition is cleared. To manually place a port into auto mode from any other mode, set the corresponding port mode bits (R12h[7:0]) to [11] (Table 19).

In auto mode, the device performs detection, classification, and powers up the port automatically if a valid PD is connected to the port. If a valid PD is not connected at the port, the device repeats the detection routine continuously until a valid PD is connected.

When entering auto mode after a reset condition (state of AUTO input), the DET\_EN\_ and CLASS\_EN\_ bits (R14h[7:0], Table 22) are set to high and stay high, unless changed by software. When entering auto mode from any other mode due to a software command (programmed with R12h[7:0], Table 19, the DET\_EN\_ and CLASS\_EN\_ bits retain their previous state.



#### Semiautomatic (Semi) Mode

Enter semiautomatic mode by setting the port operating mode (R12h, Table 19) to [10]. When entering semi mode, the DET\_EN\_ and CLASS\_EN\_ bits retain their previous states. When the DET\_EN\_ and/or CLASS\_EN\_ bits are set to 1, the MAX5980 performs detection and/or classification repeatedly, but do not power up the port(s) automatically.

Setting R19h[3:0] (PWR\_ON\_, Table 26) high turns on power to the port(s) if detection and classification has successfully completed. If a port is powered down while in semiautomatic mode, the corresponding DET\_EN\_ and CLASS\_EN\_ bits are reset to 0.

#### Manual Mode

Enter manual mode by setting the port operating mode (R12h, Table 19) to [01]. Manual mode allows the software to dictate any sequence of operation. In manual mode, the Detection/Classification register (R14h, Table 22) is set to 00h, and DET\_EN\_/CLASS\_EN\_ become pushbutton bits. A port will only perform a single detection/classification cycle when DET\_EN\_/CLASS\_EN\_ are set high, and they are reset low after execution.

PWR\_ON\_ (R19h[3:0], Table 26) has the highest priority, and setting PWR\_ON\_ high at any time causes the device to immediately enter the powered mode. Setting DET\_EN\_ and CLASS\_EN\_ high at the same time causes detection to be performed first. Once in the powered state, the device ignores DET\_EN\_ and CLASS\_EN\_ commands.

#### Shutdown Mode

To put a port into shutdown mode, set the corresponding port mode bits (R12h, Table 19) to [00]. Putting a port into shutdown mode immediately turns off port power, clears the event and status bits, and halts all port operations. In shutdown mode the serial interface is still fully active; however, all DET\_EN\_, CLASS\_EN\_, and PWR\_ON\_ commands are ignored.

#### **PD Detection**

During normal operation, the device probes the output for a valid PD. A valid PD has a  $25k\Omega$  discovery signature characteristic as specified in the IEEE 802.3at/af standard. Table 1 shows the IEEE 802.3at specification for a PSE detecting a valid PD signature.

After each detection cycle, the device sets DET\_ (R04h[3:0] and R05h[3:0], Table 9) to 1 and reports the detection results in the detection status bits (see Table 13). The DET\_ bits are reset to 0 when read through the CoR (clear on read) register (R05h), or after a reset event.

During detection, the device keeps the external MOSFET off and forces two probe voltages through OUT\_. The current through OUT\_ is measured, as well as the voltage difference from AGND to OUT\_. A two-point slope measurement is used, as specified by the IEEE 802.3at/ af standard, to verify the device connected to the port. The device implements appropriate settling times to reject 50Hz/60Hz power-line noise coupling.

PARAMETER	SYMBOL	MIN	MAX	UNITS	ADDITIONAL INFORMATION
Open-Circuit Voltage	Voc	—	30	V	In detection mode only
Short-Circuit Current	ISC	_	5	mA	In detection mode only
Valid Test Voltage	Vvalid	2.8	10	V	
Voltage Difference Between Test Points	ΔV <sub>TEST</sub>	1		V	_
Time Between Any Two Test Points	tBP	2		ms	This timing implies a 500Hz maximum probing frequency
Slew Rate	VSLEW	_	0.1	V/µs	
Accept Signature Resistance	Rgood	19	26.5	kΩ	
Reject Signature Resistance	RBAD	< 15	> 33	kΩ	
Open-Circuit Resistance	Ropen	500		kΩ	
Accept Signature Capacitance	CGOOD		150	nF	—
Reject Signature Capacitance	Cbad	10	_	μF	—
Signature Offset Voltage Tolerance	Vos	0	2.0	V	
Signature Offset Current Tolerance	los	0	12	μA	

#### Table 1. PSE PI Detection Modes Electrical Requirements (IEEE 802.3at)

To prevent damage to non-PD devices, and to protect itself from an output short circuit, the device limits the current into OUT\_ to less than 2mA (max) during PD detection. In midspan mode, after every failed detection cycle, the device waits at least 2.0s before attempting another detection cycle.

#### High-Capacitance Detection

High-capacitance detection for legacy PDs is software programmable. To use the software to enable high-capacitance detection, set LEG\_EN\_ (Port GPMD registers, Table 39) to 1 during normal operation. If high-capacitance detection is enabled, PD signature capacitances up to  $100\mu$ F (typ) are accepted.

#### Power Device Classification (PD Classification)

During PD classification, the device forces a probe voltage between 15V and 20V at OUT\_ and measures the current into OUT\_. The measured current determines the class of the PD.

After each classification cycle, the device sets CLS\_ (R04h[7:4] and R05h[7:4], Table 9) to 1 and reports the classification results in the classification status bits (see Table 13). The CLS\_ bits are reset to 0 when read through the CoR (clear on read) register (R05h) or after a reset event.

If EN\_CL5 is left unconnected, the device will classify the PD based on Table 33-9 of the IEEE 802.3at standard (see Table 2). If the measured current exceeds 51mA, the device will not power the PD, but will report an overcurrent classification result and will return to IDLE state before attempting a new detection cycle.

#### Class 5 PD Classification

The device supports high power beyond the IEEE 802.3at standard by providing an additional classification (Class 5) if needed. To enable Class 5, connect EN\_CL5 to VDD and initiate a global reset or use the software to individually enable Class 5 classification for each port (R1Ch[3:0], Table 29). Once Class 5 is enabled, during classification, if the device detects currents in excess of the Class 4 upper-limit threshold, the PD will be classified as a Class 5 powered device. The PD is guaranteed to be classified as a Class 5 device for any classification current from 51mA up to the classification current-limit threshold. The Class 5 overcurrent threshold and current limit will be set automatically with ICUT\_[5:0] and ILIM\_ (see Tables 40 and 41). Leave EN\_CL5 unconnected to disable Class 5 detection and to be fully compliant to IEEE 802.3at standard classification.

#### Table 2. PSE Classification of a PD (Table 33-9 of the IEEE 802.3at Standard)

MEASURED ICLASS (mA)	CLASSIFICATION
0 to 5	Class 0
> 5 and < 8	May be Class 0 or 1
8 to 13	Class 1
> 13 and < 16	Either Class 1 or 2
16 to 21	Class 2
> 21 and < 25	Either Class 2 or 3
25 to 31	Class 3
> 31 and < 35	Either Class 3 or 4
35 to 45	Class 4
> 45 and < 51	Either Class 4 or Invalid

**MAX5980** 

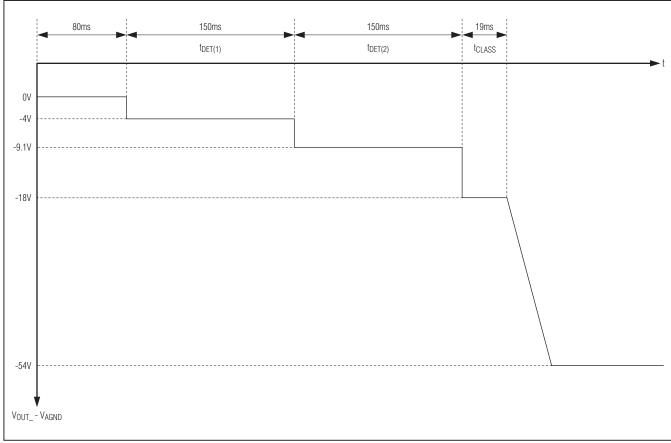


Figure 1. Detection, Classification, and Port Power-Up Sequence

#### 2-Event PD Classification

If the result of the first classification event is Class 0 to 3, then only a single classification event occurs as shown in Figure 1. However, if the result is Class 4 (or Class 5), the device will perform a second classification event as shown in Figure 2. Between the classification cycles, the device performs a first and second mark event as required by the IEEE 802.3at standard, forcing a -9.3V probing voltage at OUT\_.

#### **Powered State**

When the device enters a powered state, the tFAULT timer is reset and power is delivered to the PD. PGOOD\_ (R10h[7:4], Table 16) is set to 1 when the device enters the normal power condition. PGOOD\_ immediately resets to 0 whenever the power to the port is turned off. The power-good change bits, PG\_CHG\_ (R02h[3:0], Table 8) are set both when the port powers up and when it powers down.

#### **Overcurrent Protection**

A sense resistor, RSENSE\_, connected between SENSE\_ and SVEE\_ monitors the load current. Under normal operating conditions, the voltage across RSENSE\_ (VRSENSE\_) never exceeds the current-limit threshold, VSU\_LIM. If VRSENSE\_ exceeds VSU\_LIM, an internal current-limiting circuit regulates the GATE\_ voltage, limiting the current to ILIM = VSU\_LIM/RSENSE\_. During transient conditions, if VRSENSE\_ exceeds VSU\_LIM by more than 500mV, a fast pulldown circuit activates to quickly recover from the current overshoot. During startup, if the current-limit condition persists, when the startup timer, tSTART, times out, the port shuts off, and the TSTART\_ bit is set (R08h[3:0] and R09h[3:0], Table 11).

In the normal powered state, the device checks for overcurrent conditions as determined by V<sub>CUT</sub>. The tFAULT counter sets the maximum allowed continuous overcurrent period. The tFAULT counter increases when



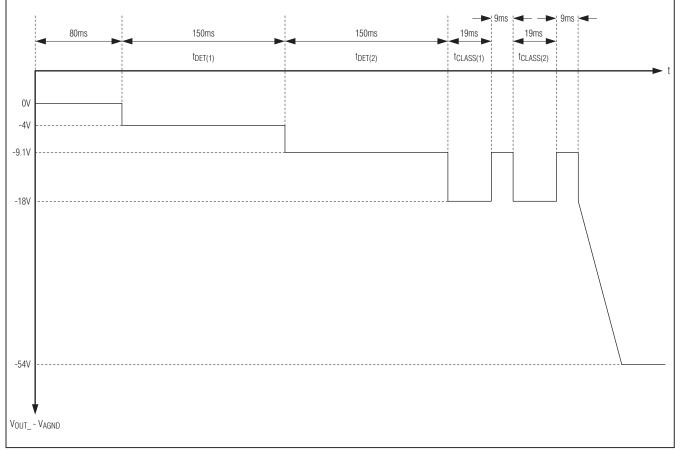


Figure 2. Detection, 2-Event Classification, and Port Power-Up Sequence

VRSENSE\_ exceeds VCUT and decreases at a slower pace when VRSENSE\_ drops below VCUT. A slower decrement for the tFAULT counter allows for detecting repeated short-duration overcurrent conditions. When the counter reaches the tFAULT limit, the device powers the port down and asserts the corresponding TCUT\_ bit (R06h[3:0] and R07h[3:0], Table 10). For a continuous overstress, a fault latches exactly after a period of tFAULT. VCUT is programmable through the ICUT\_ registers (Table 40). If a port is powered down due to a current-limit condition, during normal operation, the device asserts the corresponding ICV\_ bit (R08h[7:4] and R09h[7:4], Table 11)

After power-off due to an overcurrent fault, the tFAULT timer is not immediately reset but starts decrementing

at the same slower pace. The device allows a port to be powered on only when the tFAULT counter is at zero. This feature sets an automatic duty-cycle protection to the external MOSFET to avoid overheating.

#### **High-Power Mode**

The device features individual, port programmable highpower settings. To enable the high-power configuration for a port, set the corresponding HP\_EN\_ bit (R44h[3:0], Table 38) to 1. By default, if AUTO = 1, the HP\_EN\_ bits will be set to 1 automatically after a reset event. When enabled, each port's high-power settings can be individually configured using the corresponding Port GPMD, Port Overcurrent (ICUT), Port Current-Limit (ILIM\_), and Port High-Power Status registers (see the *Register Map and Description* section, Tables 39–42).

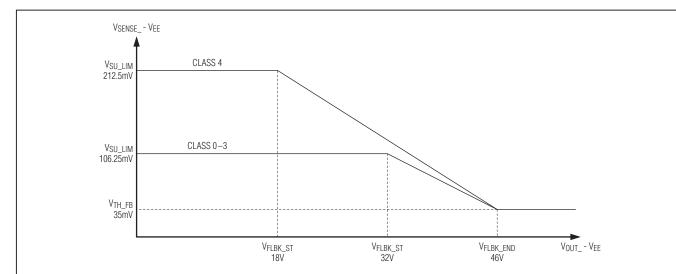


Figure 3. Foldback Current Characteristics

MAX5980

#### **Foldback Current**

During startup and normal operation, an internal circuit senses the voltage at OUT\_ and when necessary reduces the current-limit clamp voltage (V<sub>SU\_LIM</sub>) to help reduce the power dissipation through the external FET. When I<sub>LIM</sub> = 80h (Classes 0–3), foldback begins when V<sub>OUT</sub> - V<sub>EE</sub> > 32V; and when I<sub>LIM</sub> = COh (Classes 4 and 5), foldback begins when V<sub>OUT</sub> - V<sub>EE</sub> > 18V. The V<sub>SU\_LIM</sub> eventually reduces down to the minimum current-limit threshold (V<sub>TH\_FB</sub> = 35mV) when V<sub>OUT</sub> - V<sub>EE</sub> > 46V (Figure 3).

#### **MOSFET Gate Driver**

Connect the gate of the external n-channel MOSFET to GATE\_. An internal 50 $\mu$ A current source pulls GATE\_ to (VEE + 10V) to turn on the MOSFET. An internal 40 $\mu$ A current source pulls down GATE\_ to VEE to turn off the MOSFET.

The pullup and pulldown current controls the maximum slew rate at the output during turn-on or turn-off. Use the following equation to set the maximum slew rate:

$$\frac{\Delta V_{OUT}}{\Delta t} = \frac{I_{GATE}}{C_{GD}}$$

where C<sub>GD</sub> is the total capacitance between the gate and the drain of the external MOSFET. The current limit and the capacitive load at the drain control the slew rate during startup. During current-limit regulation, the device manipulates the GATE\_ voltage to control the voltage at SENSE\_ (VRSENSE\_). A fast pulldown activates if VRSENSE\_ overshoots the limit threshold (VSU\_LIM). The fast pulldown current increases with the amount of overshoot, and the maximum fast pulldown current is 50mA.

During turn-off, when the GATE\_ voltage reaches a value lower than 1.2V, a strong pulldown switch is activated to keep the MOSFET securely off.

#### Interrupt

The device contains an open-drain logic output (INT) that goes low when an interrupt condition exists. The Interrupt register (R00h, Table 6) contains the interrupt flag bits and the Interrupt Mask register (R01h, Table 7) determines which events can trigger an interrupt. When an event occurs, the appropriate Interrupt Event register bits (in R02h to R0Bh) and the corresponding interrupt (in R00h) are set to 1 and INT is asserted low (unless masked). If the master device on the I<sup>2</sup>C bus sends out an Alert Response Address, any MAX5980 device on the bus that has INT asserted will respond (see the *Global Addressing and the Alert Response Address (ARA)* section).

As a response to an interrupt, the controller can read the status of the event register(s) to determine the cause of the interrupt and take appropriate action. Each interrupt event register is paired with a Clear-on-Read (CoR) register. When an interrupt event register is read through the corresponding CoR register, the corresponding event register is reset to 0 (clearing that interrupt event). INT remains low and the interrupt is not reset when the Interrupt Event register is read through the read-only address. For example, to clear a supply event fault read ROBh (CoR) not ROAh (read-only, see Table 12). Use the INT\_CLR bit (R1Ah[7], Table 27) to clear an interrupt, or the RESET\_IC bit (R1Ah[4]) to initiate software resets.



#### **Undervoltage and Overvoltage Protection**

The device contains undervoltage and overvoltage protection features, and the flag bits can be found in the Supply Event register (R0Ah and R0Bh, Table 12) and the Watchdog register (R42h, Table 36). An internal VEE undervoltage lockout circuit keeps the MOSFET off and the device in reset until VAGND - VEE exceeds 28.5V for more than 3ms. An internal VEE overvoltage circuit shuts down the ports when VAGND - VEE exceeds 62.5V. The digital supply also contains an undervoltage lockout that triggers when VDD - VEE  $\leq$  2V.

#### **DC Disconnect Monitoring**

The DC disconnect monitoring settings are found in the Disconnect Enable register (R13h, Table 21). To enable DC disconnect, set either the ACD\_EN\_ or DCD\_EN\_ bit for the corresponding port to 1. To disable the DC disconnect monitoring, both the ACD\_EN\_ and DCD\_EN\_ bit for that port must be set to 0. When enabled, if VRSENSE\_ (the voltage across RSENSE\_) falls below the DC load disconnect threshold, VDCTH, for more than tDISC, the device turns off power and asserts the DIS\_ bit for the corresponding port (R06h[7:4] and R07h[7:4], Table 10).

#### **VDD Power Supply**

The device has an internally regulated, 3.3V digital supply that powers the internal logic circuitry. VDD has an undervoltage lockout (VDD\_UVLO) of 2V, and an undervoltage condition on VDD keeps the device in reset and the ports shut off. When VDD has recovered and the reset condition clears, the VDD\_UVLO bit in the Supply Event registers is set to 1 (R0Ah[5] and R0Bh[5], Table 12). The digital address inputs, AUTO, and MIDSPAN are internally pulled up to VDD, and all digital inputs are referenced to DGND. VDD can also be used to source up to 10mA for external circuitry. For internal regulator stability, connect a 1.8k $\Omega$  resistor in parallel with a 33nF capacitor at the VDD output (Figure 4). If an external

load is to be shared among multiple MAX5980 devices, isolate the external supply bus with a series resistor (50 $\Omega$  for 3 devices, 75 $\Omega$  for 4 devices), and place a single 1µF capacitor on the bus.

#### Hardware Power-Down

The EN digital input is referenced to DGND and is used for hardware level control of device power management. During normal operation, EN should be externally pulled directly up to V<sub>DD</sub>, the 3.3V internal regulator output (see the *Typical Operating Circuit*).

To initiate a hardware reset and port power-down, pull EN to DGND for at least 100 $\mu$ s. While EN is held low, the device remains in reset and the ports remain securely powered down. Normal device operation resumes once EN is pulled up to the V<sub>DD</sub>.

#### **Thermal Shutdown**

If the device's die temperature reaches  $+140^{\circ}$ C (typ), an overtemperature fault is generated and the device shuts down. The die temperature must cool down below  $+120^{\circ}$ C (typ) to remove the overtemperature fault condition. After a thermal shutdown condition clears, the device is reset and the TSD event bit is set to a logical 1 (R0Ah[7]/R0Bh[7], Table 12).

#### Watchdog

The Watchdog register (R42h, Table 36) is used to monitor device status, and to enable and monitor the watchdog functionality. On a power-up or after a reset condition, this register is set to a default value of 16h. WD\_DIS[3:0] is set by default to 1011, disabling the watchdog timeout. Set WD\_DIS[3:0] to any other value to enable the watchdog. The watchdog monitors the SCL line for activity. If there are no transitions for 2.5s (typ), the WD\_STAT bit is set to 1 and all ports are powered down (using the individual port reset protocol). WD\_STAT must be reset before any port can be reenabled.

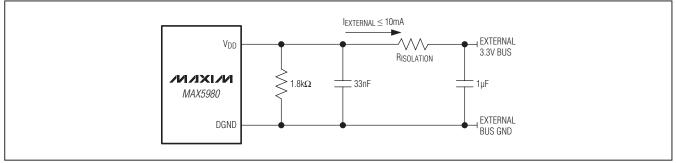


Figure 4. VDD External Power Sourcing

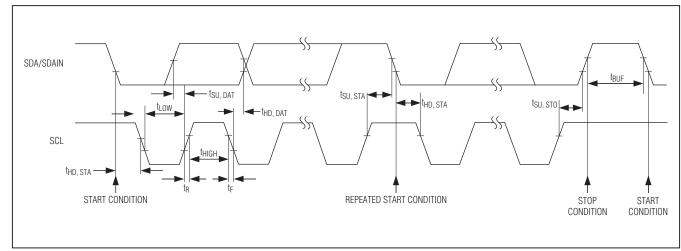


Figure 5. Serial Interface Timing Details

**MAX5980** 

#### **Table 3. Programmable Device Address Settings**

DEVICE ADDRESS						
B7	B6	B5	B4	B3	B2	B1
0	1	0	A3	A2	A1	AO

#### **Device Address (AD0)**

The MAX5980 is programmable to 1 of 16 unique slave device addresses. The three MSBs of the device address are always [010]. The 4 LSBs of the device address are programmable, and are formed by the states of the Slave Address Inputs (A0, A1, A2, and A3; see Table 3). To program the device address, connect A0, A1, A2, and A3 to a combination of V<sub>DD</sub> (logical 1) and DGND (logical 0), and initiate a device reset.

#### **I<sup>2</sup>C-Compatible Serial Interface**

The device operates as a slave that sends and receives data through an I<sup>2</sup>C-compatible, 2-wire or 3-wire interface. The interface uses a serial-data input line (SDAIN), a serial-data output line (SDAOUT), and a serial-clock line (SCL) to achieve bidirectional communication between master(s) and slave(s). A master (typically a microcontroller) initiates all data transfers to and from the device, and generates the SCL clock that synchronizes the data

transfer. In most applications, connect the SDAIN and the SDAOUT lines together to form the serial-data line (SDA). Most of the figures shown label the bus as SDA.

Using the separate input and output data lines allows optocoupling with the controller bus when an isolated supply powers the microcontroller.

The device's SDAIN line operates as an input and SDAOUT operates as an open-drain output. A pullup resistor, typically 4.7k $\Omega$ , is required on SDAOUT (3-wire mode) or SDA (2-wire mode). The SCL line operates only as an input. A pullup resistor, typically 4.7k $\Omega$ , is required on SCL if there are multiple masters, or if the master in a single-master system has an open-drain SCL output.

#### Serial Addressing

Each transmission consists of a START condition sent by a master, followed by the device's 7-bit slave address plus R/W bit, a register address byte, 1 or more data bytes, and finally a STOP condition.

generates the acknowledge bit.

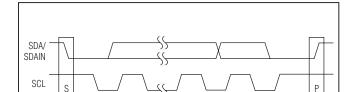
#### START and STOP Conditions

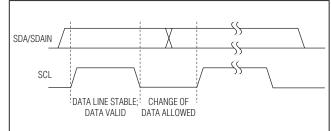
Both SCL and SDA remain high when the interface is not busy. A master signals the beginning of a transmission with a START (S) condition by transitioning SDA from high to low while SCL is high. When the master finishes communicating with the slave, the master issues a STOP (P) condition by transitioning SDA from low to high while SCL is high. The STOP condition frees the bus for another transmission (see Figure 6).

#### Bit Transfer

STOP

Each clock pulse transfers one data bit (Figure 7). The data on SDA must remain stable while SCL is high.





the recipient uses to handshake receipt of each byte of

data. Thus, each byte transferred effectively requires

9 bits. The master generates the 9th clock pulse, and

the recipient pulls down SDA during the acknowledge

clock pulse, so the SDA line is stable low during the high

period of the clock pulse. When the master transmits to

the MAX5980, the device generates the acknowledge bit. When the device transmits to the master, the master

Figure 6. START and STOP Conditions

START

Figure 7. Bit Transfer

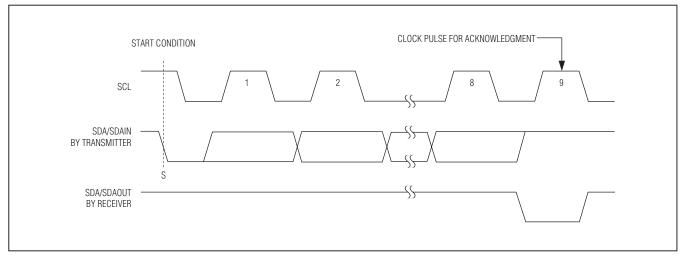


Figure 8. Acknowledge

#### Acknowledge The acknowledge bit is a clocked 9th bit (Figure 8) that

#### Slave Address

The device has a 7-bit long slave address (Figure 9). The bit following the 7-bit slave address (bit eight) is the R/W bit, which is low for a write command and high for a read command. The upper five bits of the slave address cannot be changed and are always [01000]. Using the AD0 input, the lowest two bits can be programmed to assign the device one of four unique slave addresses (see Table 3). The device monitors the bus continuously, waiting for a START condition followed by the device's slave address. When a device recognizes its slave address, it acknowledges and is then ready for continued communication.

#### Global Addressing and the Alert Reponse Address (ARA)

The global address call is used in write mode to write to the same register to multiple devices (address 60h). The global address call can also be used in read mode (61h) in the same way as the alert response address (ARA). The actual alert response address (ARA) is 0Ch. The MAX5980 slave device only responds to the ARA if its  $\overline{INT}$  (interrupt) output is asserted. All MAX5980 devices in which the  $\overline{INT}$  output is not asserted ignore the ARA.

When responding to the ARA, the device transmits a byte of data on SDAOUT containing its own address in the top 7 bits, and a 1 in the LSB (as does every other device connected to the SDAIN line that has an active interrupt). As each bit in the byte is transmitted, the device determines whether to continue transmitting the remainder of the byte or terminate transmission. The

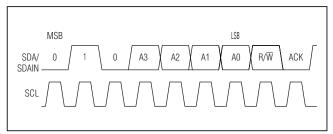


Figure 9. Slave Address

device terminates the transmission if it sees a 0 on SDA at a time when it is attempting to send a 1; otherwise it continues transmitting bits until the entire byte has been sent. This litigation protocol always allows the part with the lowest address to complete the transmission, and the microcontroller can respond to that interrupt. The device deasserts INT if it completes the transmission of the entire byte. If the device did not have the lowest address, and terminates the transmission early, the INT output remains asserted. In this way, the microcontroller can continue to send ARA read cycles until all slave devices successfully transmit their addresses, and all interrupt requests are resolved.

#### General Call

In compliance with the I<sup>2</sup>C specification, the device responds to the general call through global address 30h.

#### Message Format for Writing to the MAX5980

A write to the device comprises the device slave address transmission with the  $R\overline{W}$  bit set to 0, followed by at least 1 byte of information. The first byte of information is the command byte (Figure 10). The command byte determines which register of the device is written to by the next byte, if received. If the device detects a STOP condition after receiving the command byte but before receiving any data, then the device takes no further action beyond storing the command byte.

Any bytes received after the command byte are data bytes. The first data byte goes into the internal register of the device selected by the command byte (Figure 11). The control byte address then autoincrements (if possible; see Table 4) and then waits for the next data byte or a STOP condition.

If multiple data bytes are transmitted before a STOP condition is detected, these bytes are stored in subsequent MAX5980 internal registers as the control byte address autoincrements (Figure 12). If the control byte address can no longer increment, any subsequent data sent continues to write to that address.

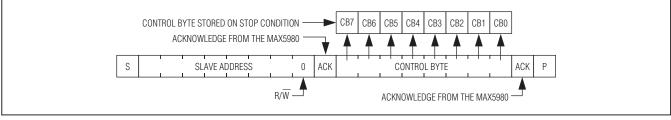


Figure 10. Write Format, Control Byte Received

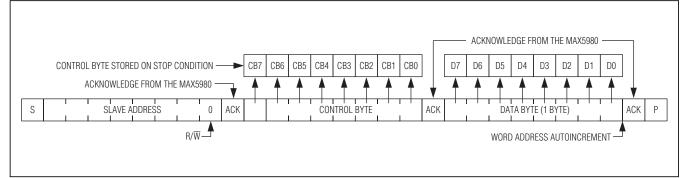


Figure 11. Write Format, Control, and Single Data Byte Written

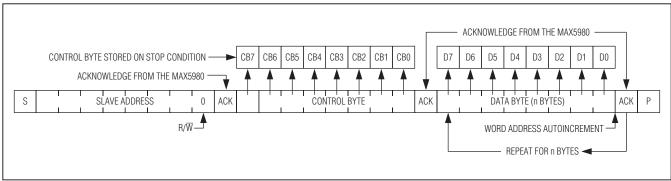


Figure 12. Write Format, Control, and n Data Bytes Written

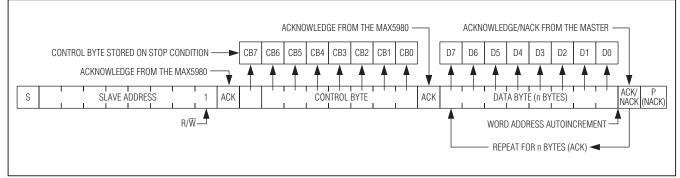


Figure 13. Read Format, Control, and n Data Bytes Read

#### Message Format for Reading

A read command for the device comprises the device slave address transmission with the R/W bit set to 1, followed by at least 1 byte of information. As with a write command, the first byte of information is the command byte. The device then reads using the internally stored command byte as an address pointer, the same way the stored command byte is used as an address pointer for

a write. This pointer autoincrements after reading each data byte using the same rules as for a write, though the master now sends the acknowledge bit after each read receipt (Figure 13). When performing read-after-write verification, remember to reset the command byte's address because the stored control byte address auto-increments after the write.



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